# **MOSFET** - Power, N-Channel, SUPERFET III, FRFET

### 650 V, 24 A, 150 mΩ

#### **Description**

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

#### **Features**

- $700 \text{ V} @ \text{T}_{\text{I}} = 150^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 121 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 43 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 400 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

#### **Applications**

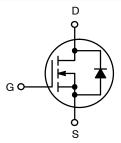
- Telecom / Server Power Supplies
- Industrial Power Supplies
- EV Charger
- UPS / Solar



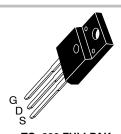
#### ON Semiconductor®

#### www.onsemi.com

V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
650 V	150 mΩ @ 10 V	24 A

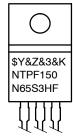


**POWER MOSFET** 



TO-220 FULLPAK CASE 221D

#### **MARKING DIAGRAM**



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code

&K = Lot Code

NTPF150N65S3HF = Specific Device Code

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

#### **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ , Unless otherwise noted)

Symbol	Parameter	Value	Unit	
$V_{DSS}$	Drain to Source Voltage		650	V
$V_{GSS}$	Gate to Source Voltage	- DC	±30	V
		- AC (f > 1 Hz)	±30	
I <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C)	24*	Α
		- Continuous (T <sub>C</sub> = 100°C)	15.2*	
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	60*	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		275	mJ
I <sub>AS</sub>	Avalanche Current (Note 2)		3.8	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		1.92	mJ
dv/dt	MOSFET dv/dt Peak Diode Recovery dv/dt (Note 3)		100	V/ns
			50	
$P_{D}$	Power Dissipation	(T <sub>C</sub> = 25°C)	192	W
		- Derate Above 25°C	1.54	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
\*Drain current limited by maximum junction temperature.

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	3.22	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTPF150N65S3HF	NTPF150N65S3HF	TO-220 FULLPACK	Tube	N/A	N/A	50 Units

<sup>1.</sup> Repetitive rating: pulse–width limited by maximum junction temperature. 2.  $I_{AS} = 3.8 \text{ A}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \le 12 \text{ A}$ ,  $di/dt \le 200 \text{ A/µs}$ ,  $V_{DD} \le 400 \text{ V}$ , starting  $T_J = 25^{\circ}\text{C}$ .

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACT	ERISTICS			•		
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V, I}_{D} = 1 \text{ mA, T}_{J} = 25^{\circ}\text{C}$	650			V
		$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 150^{\circ}\text{C}$	700			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 15 mA, Referenced to 25°C		0.62		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V			10	μΑ
		V <sub>DS</sub> = 520 V, T <sub>C</sub> = 125°C		67		
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
ON CHARACTE	RISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 0.54$ mA	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A		121	150	mΩ
9FS	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 12 A		14		S
DYNAMIC CHAI	RACTERISTICS		•		-	
C <sub>iss</sub>	Input Capacitance	.,		1985		pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		40		pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		400		pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		71		pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V			43		nC
Q <sub>gs</sub>	Gate to Source Gate Charge	$V_{DS} = 400 \text{ V}, I_{D} = 12 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 4)		13		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	(13.2.1)		17		nC
ESR	Equivalent Series Resistance	f = 1 MHz		5.0		Ω
SWITCHING CH	IARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time			21		ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}$		19		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{DD}$ = 400 V, $I_{D}$ = 12 A, $V_{GS}$ = 10 V $R_{g}$ = 4.7 $\Omega$ (Note 4)		63		ns
t <sub>f</sub>	Turn-Off Fall Time			14		ns
SOURCE-DRAII	N DIODE CHARACTERISTICS					
I <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current				24	Α
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current				60	Α
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 12 \text{ A}$			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>DD</sub> = 400 V, I <sub>SD</sub> = 12 A,		88		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$		306		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

#### TYPICAL CHARACTERISTICS

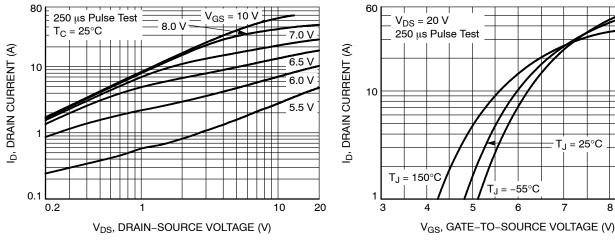


Figure 1. On-Region Characteristics



8

9

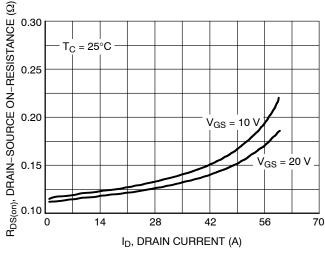


Figure 3. On-Resistance Variation vs. Drain **Current and Gate Voltage** 

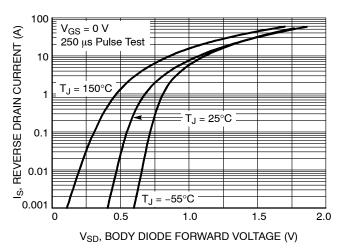


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

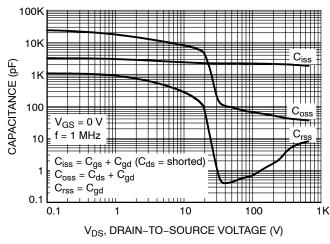


Figure 5. Capacitance Characteristics

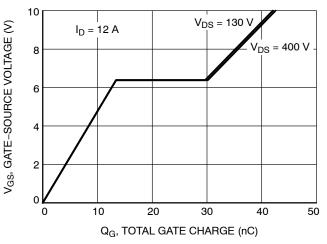


Figure 6. Gate Charge Characteristics

#### **TYPICAL CHARACTERISTICS**

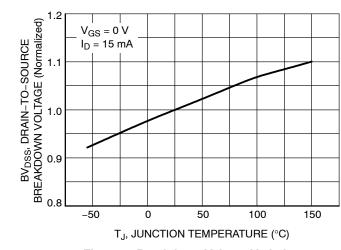


Figure 7. Breakdown Voltage Variation vs. Temperature

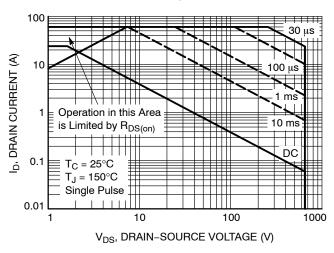


Figure 9. Maximum Safe Operating Area

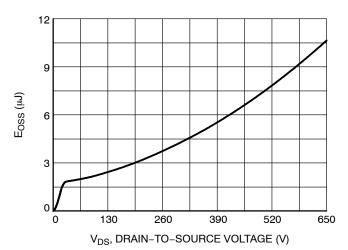


Figure 11. E<sub>OSS</sub> vs. Drain-to-Source Voltage

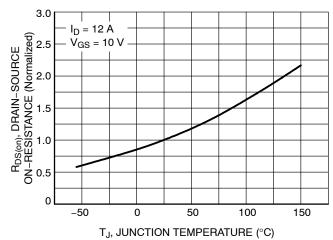


Figure 8. On–Resistance Variation vs. Temperature

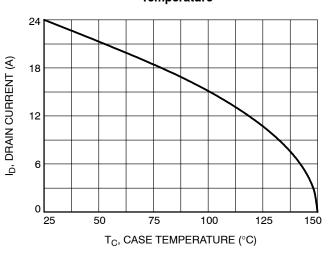


Figure 10. Maximum Drain Current vs. Case Temperature

#### **TYPICAL CHARACTERISTICS**

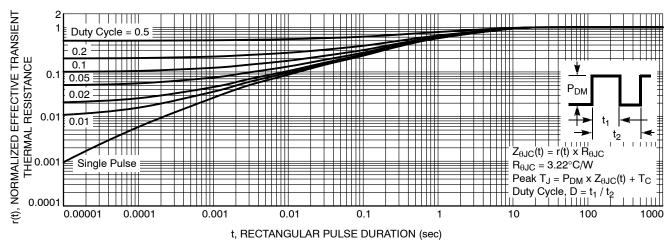


Figure 12. Transient Thermal Response Curve

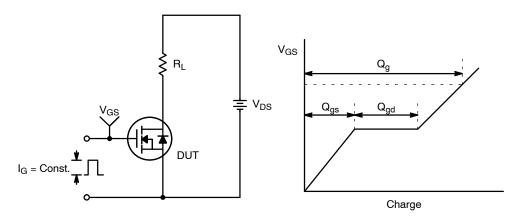


Figure 13. Gate Charge Test Circuit & Waveform

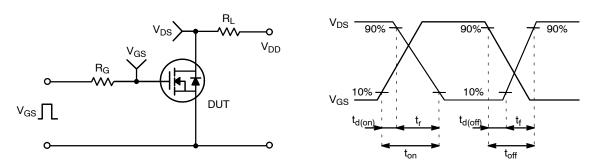


Figure 14. Resistive Switching Test Circuit & Waveforms

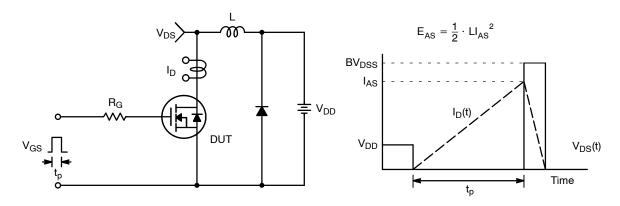


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

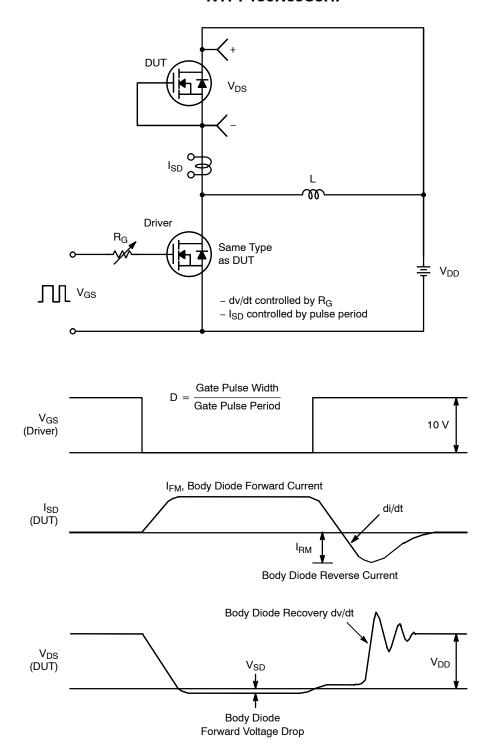


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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# **MECHANICAL CASE OUTLINE**





SCALE 1:1

#### TO-220 FULLPAK CASE 221D-03 ISSUE K

**DATE 27 FEB 2009** 

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100	BSC	2.54 BSC	
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

# -T- SEATING PLANE -B--Y-– **D** з PL

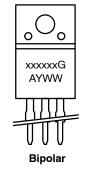
| 🕁 | 0.25 (0.010) M | B M | Y

#### **MARKING DIAGRAMS**

STYLE 1: PIN 1. GATE STYLE 2: PIN 1. BASE 2. DRAIN 2. 3. SOURCE

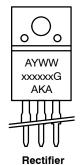
STYLE 3: PIN 1. ANODE 2. COLLECTOR 3. EMITTER CATHODE
 ANODE STYLE 5: PIN 1. CATHODE

STYLE 6: PIN 1. MT 1 2. MT 2 3. GATE STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE ANODE 3. CATHODE



xxxxxx = Specific Device Code G = Pb-Free Package = Assembly Location Α

Υ = Year = Work Week WW



= Assembly Location

Υ = Year WW = Work Week XXXXXX = Device Code = Pb-Free Package G AKA = Polarity Designator

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